

SPECIFICATIONS

FINISHED BOARD TOTAL THICKNESS IS 1.2MM (1.0 to 1.6 acceptable)

#stackup based on
Würth HDI4_1-2-1_1,22_35_V2.12
https://www.we-online.com/files/pdf1/hdi4_1-2-1_122_35_v2.12.pdf
outer copper thickness 17u acceptable for small BGA pads

ATTENTION 0.35mm BGA on TOP
board manufacturer may adjust pad size and solder mask, as long as solder mask remains between pads

MATCHED IMPEDANCE:
100R +/- 20% DIFF IMPEDANCE, tracks on bottom layer

SILKSCREEN COLOR: WHITE (Yellow acceptable)
SOLDER MASK COLOR: BLACK / DARK BLUE (do not sacrifice solder mask precision for color, feedback if needed)
BOARD FINISH: ENIG / ENEPIG

Layer	Name	Material	Thickness	Board Layer Stack
	Top Overlay			
	Top Solder	WE-SM-0001	0.015mm	
1	Top Side	WE-ED-0008	0.030mm	
	Dielectric 1	WE-PP-0003	0.065mm	
2	Inner Layer 1	WE-ED-0004	0.035mm	
	Core 1	WE-CO-0017	0.930mm	
3	Inner Layer 2	WE-ED-0004	0.035mm	
	Dielectric 2	WE-PP-0003	0.065mm	
4	Bottom Side	WE-ED-0008	0.030mm	
	Bottom Solder	WE-SM-0001	0.015mm	
	Bottom Overlay			
Total board thickness:			1.220mm	



